BuLED

BuLED-50Fx LED light accessory to replace MR16 fittings

Features VS Benefits

* BuLED-50Fx LED light accessory includes one LED cooler and one LED housing to be assembled with LED modules to replace MR16.
* Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
* For spotlight and downlight designs form 500 to 1400 lumen.
* Thermal resistance range Rth 4.8°C/W.
* Heatsink Diameter 48mm - Standard height 50mm , Other heights on request.
* Housing Diameter 50mm - Standard height 50mm , Other heights on request.
* Forged from highly conductive aluminum.

Zhaga Book 3 Spot Light Modules: Xicato ,Bridgelux ,Citizen ,Lumileds ,Lumens , Seoul ,LG Innotek ,Prolight Opto ,Samsung ,Tridonic ,Luminus ,Edison;

1) Xicato: XSM, XIM,XTM series;
2) Bridgelux: ESS, ESR, Vero 10, Vero 13 series;
3) Citizen: CLL022, CLU024, CLL026, CLU028 series;
4) Lumileds: Luxeon COB's 1203, 1204,Luxeon K series;
5) Lumens: ERC1507 and ERC1512 series;
6) Seoul: Semiconductor ZC6, ZC12 series;
7) LG Innotek: LEMWM18 10W, 13W series;
8) Tridonic: TALEXX SLE series;
9) Prolight Opto: PABS, PABA, PACB, PANA series;
10) Luminus: Cxx-6 and Cxx-9 series;
11) Samsung: LC013 series;
12) Edison: EdiLex II COB LED series;

Order Information

Example:BuLED-50Fx-B

Example:BuLED-50Fx - 1

1 Anodising Color

B-Black

C-Clear

Z-Custom

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior

Product deta table

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Model No.	BuLED-50Fx
Heatsink Size	Φ48xH50mm
Housing Size	Φ50xH50mm
Material (Heatsink + Housing)	AL1070 + AL6063-T5
Finish	Black Anodized
Weight (g)	95.0
Dissipated power (Ths-amb,60℃)	12.5 (W)
Cooling surface area (mm^2)	54500
Thermal Resistance (Rhs-amb)	4.8 (°C/W)

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E-fax: +86-(020)28819702 ext22122
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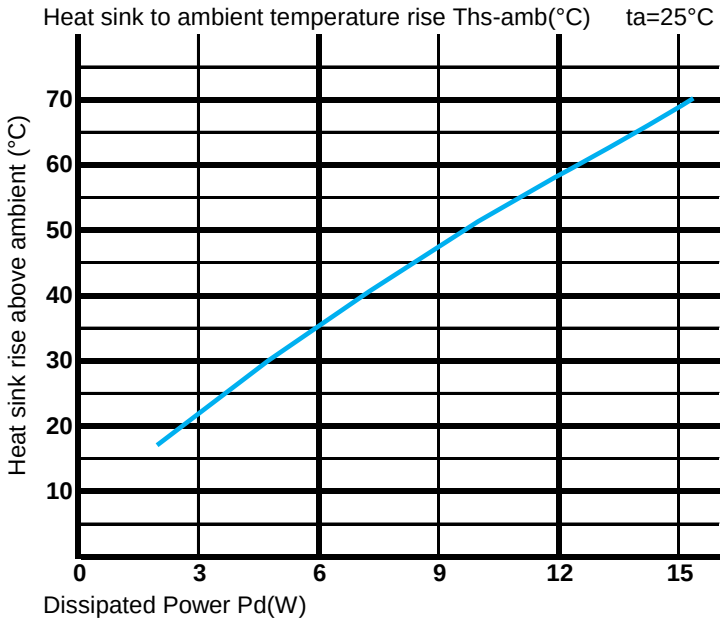
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

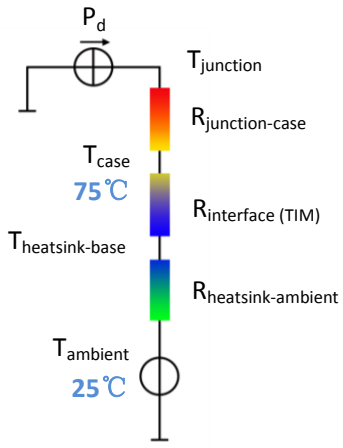
*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		BuLED-50Fx	
Dissipated Power Pd(W)	3.0	7.7	23.0
	6.0	5.8	35.0
	9.0	5.2	47.0
	12.0	4.8	58.0
	15.0	3.9	58.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.
Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.
Geometric shapes are different, the thermal resistance is different.
Formula: θ=(Ths−Ta)/Pd
θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$$

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